

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Hua Ji
Assignee: Mosel Vitelic Corporation
Title: HDP CVD Process For Void-Free Gap Fill Of A High Aspect Ratio Trench
Serial No.: 10/080,468 Filing Date: February 22, 2002
Examiner: Anh D. Mai Group Art Unit: 2814
Docket No.: M-12589US

Irvine, California
August 12, 2002

COMMISSIONER FOR PATENTS
Washington, D. C. 20231

CHANGE OF CORRESPONDENCE ADDRESS

Dear Sir:

Please direct all correspondence in the above-identified application and with respect to any patent that issues on this application to the undersigned at this address:

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Certification of Facsimile Transmission

I hereby certify that this paper is being facsimile transmitted to the U.S. Patent and Trademark Office on the date shown below.

Sandy Kim

Sandy Kim

August 12, 2002

Respectfully submitted,

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